

ABSTRACT OF THE DISCLOSURE (FIG. 3)

"APPARATUS FOR FORMING COATING FILM FOR
SEMICONDUCTOR PROCESSING"

Disclosed is an apparatus for forming a coating
5 film for semiconductor processing, comprising holding
means for holding a substrate, coating solution supply
means arranged to face one main surface of the
substrate held by said holding means and provided with
a discharge port for supplying a coating solution onto
10 said one main surface of the substrate, said coating
solution forming a band-like stream having a width
smaller than that of the substrate, moving means for
moving said coating solution supply means in parallel
and relative to the substrate held by the holding means
15 to form a coating region and a non-coating region on
the one main surface of the substrate, and clearance
retaining means for maintaining constant the distance
between the discharge port of the coating solution
supply means and the one main surface of the substrate.